



ThinFlex

ThinFlex Corporation

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ThinFlex-A-2005RD Adhesiveless Double Sided Copper Clad Laminate (Halogen Free)

ThinFlex-A-2005RD is an adhesiveless double sided (D/S) metal clad polyimide film, furnished in the form of roll laminate with RA copper on both sides. ThinFlex-A-2005RD adhesiveless D/S composites are designed for a wide variety of flexible circuit applications which require advanced material performance, temperature resistance, fine pitch, and high reliability.

1. Product Characteristics:

- * Excellent dimensional stability
- * Excellent flexibility
- * Finer line etch ability
- * Low moisture absorption
- * Excellent flammability (Flame class UL 94V-0; UL File No. E219724)
- * Excellent chemical resistance
- * Excellent thermal, mechanical, and electrical properties

2. Specifications:

A - 20 05 R D

Product A : D/S FCCL	Thickness of PI 20 : 2.0 mil	Thickness of Cu 05 : 0.5oz	Cu Type R : RA	Structure Double-sided
Supply Size	W: 250/500 ± 2mm; L: 400~700 ± 2mm (sheet type) W: 250/500 ± 2mm; L: 50 +2/-0m (roll type)			

*Other thicknesses and dimensions are available on customers' demand.



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3. Construction:

Copper foil

Polyimide film

4. Properties:

Copper foil

Test item	Unit	A-2005RD	Test Method	
Peel Strength				
As Received	Kgf/cm	≥ 0.8	IPC-TM650 2.4.9 B	
Solder Float	Kgf/cm	≥ 0.8	IPC-TM650 2.4.13 B	
After Temp. Cycling	Kgf/cm	≥ 0.8	IPC-TM650 2.4.9	
Chemical Resistance	Kgf/cm	≥ 0.8	IPC-TM650 2.3.2	
Tensile Strength (Base Film)	kg/mm ²	50	IPC-TM-650 2.4.19	
Elongation (Base Film)	%	90	IPC-TM-650 2.4.19	
Tensile Modulus (Base Film)	kg/mm ²	730	ASTM D882	
Initial Tear Strength (Base Film)	g	-	IPC-TM-650 2.4.16	
Propagation Tear Strength (Base Film)	g	-	IPC-TM-650 2.4.17.1	
Flexural Endurance, MIT				
M.D.	Times	NA	JIS-C 6471, 0.8mmR, 0.5kg	
T.D.	Times	NA	JIS-C 6471, 0.8mmR, 0.5kg	
Electrical Properties				
Surface Resistance	Ω	~10 ¹¹	IPC-TM650 2.5.17	
Volume Resistance	Ω-cm	~10 ¹²	IPC-TM650 2.5.17	
Insulation Resistance	Ω	~10 ⁹	IPC-TM650 2.6.3.2	
Dielectric Strength	kV/mil	6.9	ASTM-D149	
Physical and Thermal Properties				
Dimensional Stability	M.D.	%	-0.1~0.1	IPC-TM650 2.2.4C
	T.D.	%	-0.1~0.1	IPC-TM650 2.2.4C
CTE	ppm/°C	19.3	ThinFlex	
T _g	°C	250	ThinFlex	
Solder Float	10sec at 288°C (550°F)	-	Pass	IPC-TM650 2.4.13
Ion Migration	1000hr/85%/85°C/50V DC	-	Pass	ThinFlex
Moisture Absorption Test		%	1.1	IPC-TM650 2.6.2
Chemical Resistance-single		%	Pass	IPC-TM650 2.3.2
Thickness tolerance		%	±10%	ThinFlex
UL Flame Class		-	94V-0	UL

* Above data are typical values, and are not guaranteed values.



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5. Storage:

ThinFlex-A-2005RD will meet its shelf-life for at least 12 months after arrival at the user's factory when stored in the original packaging at temperatures of below 25°C and below 70% humidity. The products do not need refrigeration and should not be frozen.

Note: The information and data contained in this technical literature is believed to be accurate and is offered in good faith for the benefit of the user. The user should make his own tests to verify the suitability of this product for any application before its use. All data are typical values only and subject to change without notice.

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